



Material Composition Declaration

EPC2204A

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/10/2023
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	5.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.3254	78.6114	81.9251	786114
	Silicon oxide	7631-86-9	0.0278	0.5047		5047
	Silicon nitride	12033-89-5	0.0081	0.1465		1465
	Gallium nitride	25617-97-4	0.0215	0.3911		3911
	Aluminum	7429-90-5	0.0414	0.7519		7519
	Aluminum nitride	24304-00-5	0.0046	0.0831		831
	Titanium	7440-32-6	0.0009	0.0159		159
	Titanium nitride	25583-20-4	0.0398	0.7234		7234
	Copper	7440-50-8	0.0007	0.0125		125
	Tungsten	7440-33-7	0.0051	0.0932		932
	Polyimide		0.0325	0.5912	5912	
Under Bump Metal	Titanium	7440-32-6	0.0007	0.0122	0.1337	122
	Copper	7440-50-8	0.0067	0.1215		1215
Solder Bump	Copper	7440-50-8	0.0669	1.2150	17.9412	12150
	Nickel	7440-02-0	0.0399	0.7248		7248
	Tin	7440-31-5	0.8646	15.7134		157134
	Silver	7440-22-4	0.0158	0.2880		2880
Sum in total:			5.5022	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.